

## Power-Signal-Terminal RM 5,00/2,00mm, Buchsenkontakte, gerade Power-Terminal 5.00/2,00mm Pitch, Female, Straight

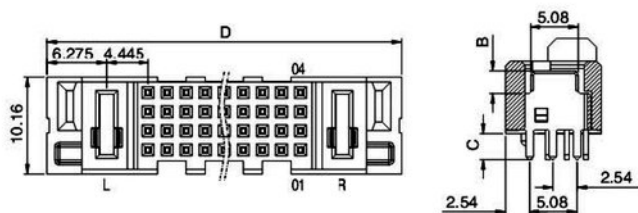
### Technische Daten / Technical Data

Isolierkörper	Thermoplast, UL94 V-0
Insulator	Thermoplastic, UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni
Contact Surface	Acc. to plating options, over Ni
Nennspannung	Power: 600 V AC / 848 V DC Signal: 300 V AC / 424 V DC
Voltage Rating	Power: 600 V AC / 848 V DC Signal: 300 V AC / 424 V DC
Nennstrom	Power: 24,7 A / Signal: 1 A
Current Rating	Power: 24.7 A / Signal: 1 A
Temperaturbereich	-55° ... +105° C
Temperature Range	-55° ... +105° C
Verarbeitung	260°C für 10s
Processing	260°C for 10s

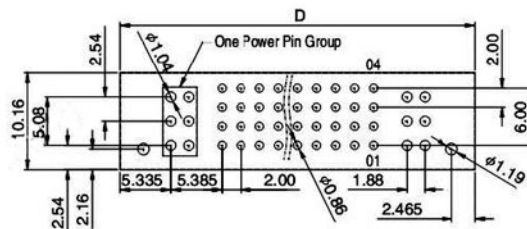
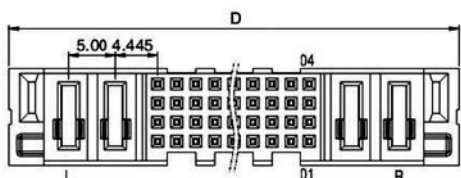


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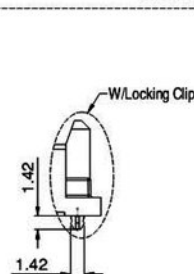
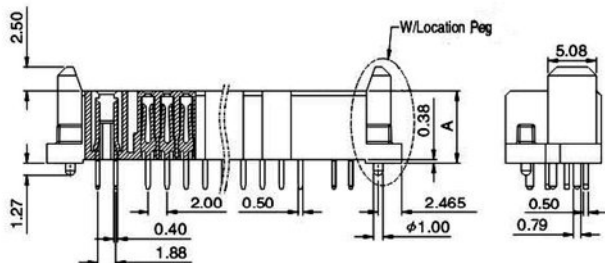
ectors :  
(24/80)



Power Pins/End	D		
	16 Signal Pins	24 Signal Pins	80 Signal Pins
01	27.44	31.44	59.44
02	37.44	41.44	69.44



Recommended PCB Layout



<b>Series</b>	<b>Power C.*</b>	<b>Signal C.*</b>	<b>Power C.*</b>	<b>Terminals*</b>	<b>Plating P.C.*</b>	<b>Plating S.C.*</b>	<b>Loc. Opt.*</b>	<b>Packaging*</b>
<b>454</b>	<b>01</b>	<b>24</b>	<b>01</b>	<b>11</b>	<b>00</b>	<b>00</b>	<b>10</b>	<b>ST</b>
	01 02 Contacts Left	16 24 80 Contacts	01 02 Contacts Right	10 A=7.58 B=2.37 C=2.72mm 11 A=7.58 B=2.37 C=3.52mm 12 A=7.58 B=2.37 C=4.32mm	00 Au flash 50 Sn 60 Sel. Au/Sn 610 Sel. Au 10µ"/ Sn	00 Au flash 50 Sn 60 Sel. Au/Sn 610 Sel. Au 10µ"/ Sn	10 Locating Pegs 20 Locking Clips	ST TRAY

\* Dies ist ein **Bestellbeispiel** -  
bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** -  
please replace by your specifications.

### Lieferformen / Packaging Options:

ST In Stangen / In tubes  
TRAY Auf Tray / On tray

# Informationen zum Reflow-Lötverfahren

## Reflow Soldering Information

### Reflow-Lötempfehlung

#### Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150°C
Temperatur Maximum $T_{Smax}$	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich $T_L$	217°C
Verweildauer oberhalb $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur $T_P$	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur $T_P$	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150°C
Maximum Temperatur $T_{Smax}$	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature $T_L$	217°C
Duration above $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature $T_P$	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. $T_P$	Max. 8min

